



特点

- * 外形尺寸: 61.0 × 57.9 × 12.7mm
- * 工业标准半砖封装和引脚
- * 双路输出
- * 基板工作温度 100℃

Features

- * Size: 2.40 × 2.28 × 0.50 inch
- * Industry Standard Half-Brick Package and Footprint
- * Dual Outputs
- * 100℃ Baseplate Operation

输入特性 (Input)

注释 (Notes and Conditions)

输入电压范围 (Input Voltage Range)	36~72Vdc	80Vdc Max
输入欠压保护 (Input Undervoltage Protection)	< 36Vdc	
遥控功能 (Remote On/Off Function)		
1) 正逻辑 (Positive Logic) 开启 (On)	高电平 (2.5 ~ 18Vdc) 或悬空 (High Level or Open Circuit)	相对于 -Vin (Reference to -Vin)
关闭 (Off)	低电平 (< 1.4Vdc) 或与 -Vin 短接 (Low Level or Connect to -Vin)	
2) 负逻辑 (Negative Logic) 开启 (On)	低电平 (< 0.4Vdc) 或与 -Vin 短接 (Low Level or Connect to -Vin)	相对于 -Vin (Reference to -Vin)
关闭 (Off)	高电平 (1.4 ~ 18Vdc) 或悬空 (High Level or Open Circuit)	

输出特性 (Output)

注释 (Notes and Conditions)

输出电压精度 (Voltage Set-Point Accuracy)	Vo1 : ± 1% Vo2 : ± 2%	V _{in} nom and I _o nom
输出电压调节范围 (Output Voltage Trim Range)	Vo1 : ± 10% Vo2 : ± 10%	跟随 Vo1 (Follow Vo1)
源效应 (Line Regulation)	Vo1 : ± 0.2% Vo2 : ± 1% Vo2 : ± 2%	I _{o1} nom, I _{o2} nom 或 I _{o1} max, I _{o2} min I _{o1} nom, I _{o2} nom I _{o1} =1A, I _{o2} max
负载效应 (Load regulation)	Vo1 : ± 0.4% Vo1 : ± 0.4% Vo2 : ± 1% Vo2 : ± 5%	I _o min~I _o nom, V _{in} nom, Balance load 10%~100% I _{o1} nom, V _{in} nom, I _{o2} min I _o min~I _o nom, V _{in} nom, Balance load 10%~100% I _{o2} nom, V _{in} nom, I _{o1} =1A
两路输出过压保护 (Dual Outputs Overvoltage Protection)	115%~140%Vo	P _o < P _o max
输出过流保护点 (Current Limit Threshold)	110%~140%I _o	V _{in} nom, I _{o1} +I _{o2}
短路保护 (Short-Circuit Protection)	间歇可恢复 (Hiccup, Automatic Recovery)	
瞬态响应 (Dynamic Response)		
过冲幅度 (Peak Deviation)	± 5%Vo	25%-50%-25% of I _o nom
恢复时间 (Settling Time)	200 μs	and 50%-75%-50% of I _o nom

一般特性 (General)

注释 (Notes and Conditions)

温度系数 (Temperature coefficient)	± 0.02%/℃	
隔离电压 (Isolation voltage)		
输入与输出 (Input-output)	1500Vdc 1min	
输入与基板 (Input-Baseplate)	1000Vdc 1min	
输出与基板 (Output-Baseplate)	500Vdc 1min	
工作基板温度 (Operating Baseplate Temperature)	-25℃~+100℃	
贮存温度 (Storage Temperature)	-40℃~+125℃	
冷却方式 (Cooling)	加装散热器或强制风冷	Attach Heatsink or Forced Convection
过温保护 (Thermal Shutdown Range)	100℃~110℃	基板温度 (Baseplate Temperature)
平均故障间隔时间 (MTBF)	2 × 10 ⁵ h	MIL-HDBK-217

注: 除非另有说明, 指标一般在标称输入电压、满载和 25℃ 基板温度下测得。

Note: All specifications are typical at nominal input, full load at 25℃ baseplate temperature unless otherwise stated.

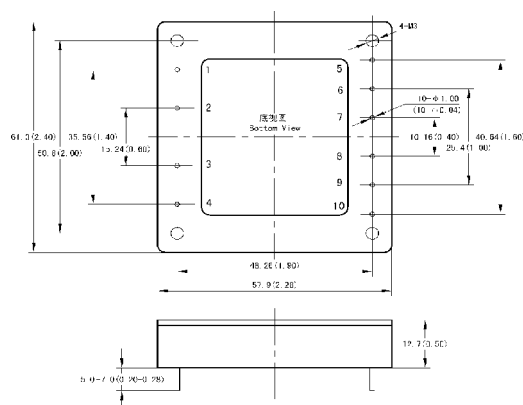
型号列表 (Models)

产品型号 (Model Number)	标称输入电压 (Input Voltage) Vdc	标称输出电压 (Output Voltage) Vdc	标称负载 (Output Current) A	最大输出功率** (Output Power) W	最大输出功率 (Output Power) W	效率 (Efficiency) %	输出杂音电压峰峰值 (Ripple and Noise) mVp-p
HDR-0752DC	48	12/-12	3.25/3.25	6/5	78	85	150
HDR-0753DC	48	15/-15	2.5/2.5	4.5/4	75	86	150
HDR-L0752DC*	48	12/-12	3.25/3.25	6/5	78	85	150
HDR-L0753DC*	48	15/-15	2.5/2.5	4.5/4	75	86	150

- 注: 1. *: "-L" 型号遥控功能为负逻辑。(Model with "-L" is Negative Logic.)
 2. **: Vout= ± 12V, Io2min=0.33A 时 Io1max=6A, Io1=1.5A 时 Io2max=5A;
 Vout= + 15V, Io2min=0.33A 时 Io1max=4.5A, Io1=1A 时 Io2max=4A.

安装尺寸 (Mechanical Drawing)

尺寸单位是 mm(inches); All Dimensions in mm (inches)



引脚定义 (Pin Definition)

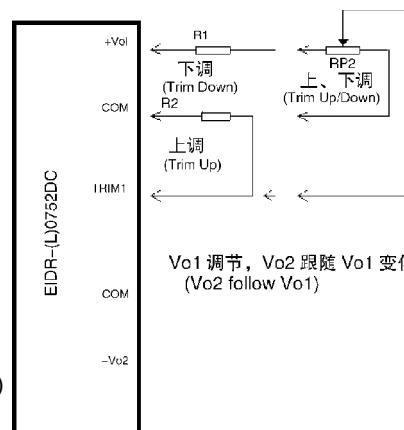
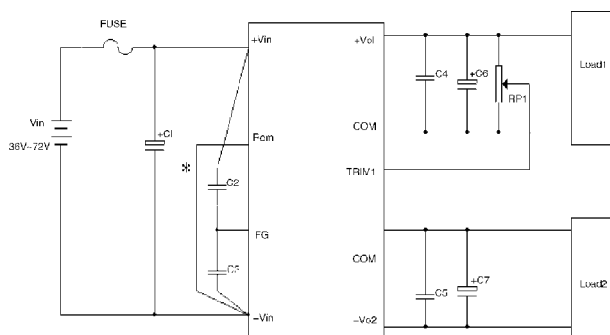
Pin No.	Function	Pin No.	Function
1	-Vin	6	-S
2	FG	7	Trim
3	Rem	8	+S
4	+Vin	9	+Vout
5	-Vout		

未注公差按下表

(Tolerances Unless Otherwise Specified)	
mm	inches
.x ±0.5	.xx ±0.02
.xx ±0.13	.xxx ±0.005

效率负载曲线 (Curve of Efficiency vs. Load)

输出电压调节 (Output Voltage Trim)



*: 负逻辑时, Rem 和 -Vin 连接 (Rem and -Vin are connected for negative logic)

FUSE 推荐值 (Recommended): 250V/5A

C1 推荐值 (Recommended): 33 μ F/100V

C2, C3 推荐值 (Recommended): 4700pF/2kV

C4, C5 推荐值 (Recommended): 1 μ F/50V (陶瓷电容) (Ceramic Capacitor)

C6, C7 推荐值 (Recommended): 容量 < 6800 μ F, 耐压 > 25V。

RP1: 输出上下调节用电位器 (输出无需调节时不用)。 (Resistance for Trim1)